# Nomenclature for DDR3 Module

**Ver.: 1.2**

| 1 2 | 3 | 4 | 5 | 6 7 | 8 | 9 | 10 | 11 12 | 13 14 | 15 | 16 | 17 18 | 19 | 20 | 21 | 22 |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| HX | M | S | H | 8G | U | 1 | 3 | A1 | F1 | C | - | 08 | E | I | _ | C1 |

For 8GB RDIMM

**Identifier**
HX = UnilC Identifier

**Product Group**
M = Module

**Application**
S = Standard
H = with heat sink

**Product Family**
H = DDR3

**Density**
1G = 1 GB
2G = 2 GB
4G = 4 GB
8G = 8 GB
16 = 16 GB
32 = 32 GB
64 = 64 GB

**Module Type**
P = Parity RDIMM
S = SODIMM
U = UDIMM
E = ECC UDIMM
X = ECC SODIMM

**Number of Ranks of Module**
0 = 1 Rank
1 = 2 Ranks
2 = 4 Ranks
3 = 8 Ranks
4 = 16 Ranks

**Number of IOs of Device**
2 = x4
3 = x8
4 = x16
5 = x32

**Register Code**
C1 = TI
Blank = Montage

I = Industrial
Blank = commercial

**Latencies**
D = 5-5-5
E = 6-6-6
F = 7-7-7
G = 8-8-8
H = 9-9-9
J = 10-10-10
K = 11-11-11

**Datarate**
8 = DDR3-800
10 = DDR3-1066
13 = DDR3-1333
16 = DDR3-1600

**Power**
- = Standard
L = Low power

**Temperature Range & PCB Size**
C = Standard PCB
T = Tall PCB
V = VLP PCB

**Package Technology**
F1 = Planar FBGA
F2 = 1x2 Stacked Die in FBGA
F4 = 1x4 Stacked Die in FBGA

**Die Revision**
A1 = Frist product
A2 = Second product
A3 = Third product